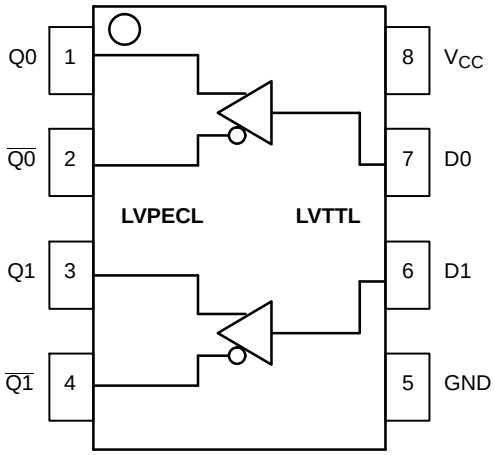

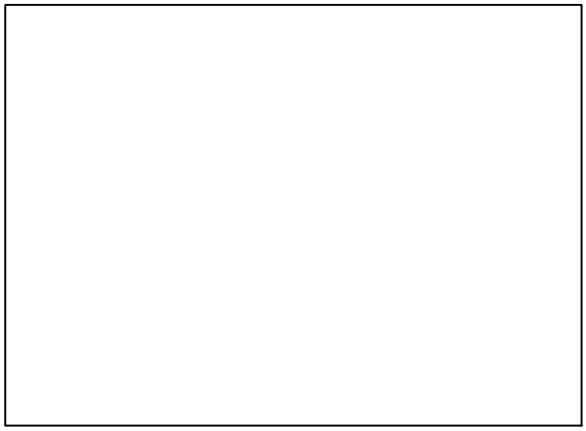

Figure 1. 8−Lead Pinout (Top View) **and Logic Diagram**

Table 6. AC CHARACTERISTICS (V_{CC} = 3.0 V to 3.6 V, GND = 0.0 V (Note 5))

Symbol	Characteristic	−40 C			25 C			85 C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (Figure 2)	0.8									

Figure 3. Typical Phase Noise Plot at $f_{carrier}$ = 25 MHz

Figure 4. Typical Phase Noise Plot at $f_{carrier}$ = 156.25 MHz

The above phase noise plots captured using Agilent E5052A show additive phase noise of the MC100EPT22 device at frequencies 25 MHz and 156.25 MHz respectively at an operating voltage of 3.3 V in room temperature. The RMS Phase Jitter contributed by the device (integrated between 12 kHz and 20 MHz; as shown in the shaded region of the plot) at each of the frequencies is 158 fs and 48 fs respectively. The input source used for the phase noise measurements is Agilent E8663B.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

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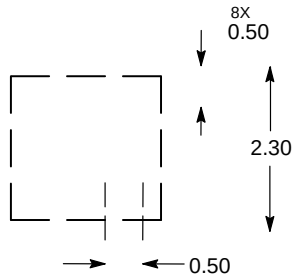

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the m1 □ Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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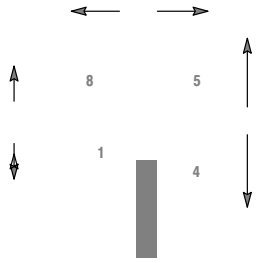

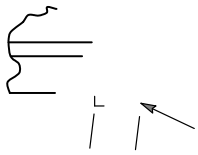

SEATING
PLANE

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CASE 948R−02
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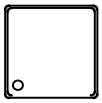

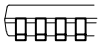

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B				
